

CLAIMS

1. An integrated circuit (IC1) comprising functional logic (1) and Flash-EEPROM (2) coupled to at least one connection pad of said integrated circuit,

5           **characterized in that** several connection pads (CP1, CP2) are arranged into a pad arrangement (PAD: PAD1, PAD2, PAD3, PAD4),

**and in that** said integrated circuit (IC1) further comprises mixing devices (IMUX, OMUX) adapted to couple said functional logic (1) and said Flash-EEPROM (2) to a connection pad of said pad arrangement  
10       (PAD).

2. The integrated circuit according to claim 1,

**characterized in that** said pad arrangement (PAD) comprises at least two juxtaposed connection pads (CP1, CP2) interconnected  
15       electrically.

3. The integrated circuit according to claim 2,

**characterized in that** said two juxtaposed connection pads (CP1, CP2) have substantially the same design.

20           4. The integrated circuit according to claim 1,

**characterized in that** said pad arrangement (PAD) comprises a first connection pad (CP1) adapted to be used for probing and for bonding, and a second connection pad (CP2) adapted to be used only for probing.

25           5. An integrated circuit (IC2) comprising functional logic (1) and Flash-EEPROM (2) coupled to at least one connection pad of said integrated circuit,

**characterized in that** said integrated circuit (IC2) further  
30       comprises a first set of dedicated connection pads (PAD10, PAD11, PAD12)

coupled to said functional logic (1), and a second set of dedicated connection pads (PAD21, PAD22) coupled to said Flash-EEPROM (2).

- 5                   6. The integrated circuit according to any of the claims 1 or 5,  
                  **characterized in that** said functional logic (1) comprises analog  
                  logic and digital logic.